

Title (en)

ATTACHMENT OF SEMICONDUCTOR DIE TO LEAD FRAME BY MEANS OF AN ADHESIVE RESIN.

Title (de)

VERBINDUNG ZWISCHEN EINEM HALBLEITERPLÄTTCHEN UND EINEM LEITERRAHMEN MITTELS EINES KLEBEHARZES.

Title (fr)

FIXATION D'UN DE DE SEMICONDUCTEUR A UN CADRE DE MONTAGE A CONDUCTEURS AU MOYEN D'UNE RESINE ADHESIVE.

Publication

EP 0333734 A1 19890927 (EN)

Application

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Priority

US 93060086 A 19861113

Abstract (en)

[origin: WO8803704A1] Semiconductor packages are fabricated by first depositing an adhesive resin (6) composition on the paddle (8) of a lead frame (2), activating the adhesive resin by rapidly raising its temperature and then depositing a die (16) on the activated adhesive. Conventional wire bonding and encapsulating steps follow to afford the semiconductor package.

Abstract (fr)

On fabrique des modules à semiconducteurs en déposant d'abord une composition de résine adhésive (6) sur la plaquette (8) d'un cadre de montage à connecteurs (2), en activant la résine adhésive par élévation rapide de sa température, puis en déposant un dé (16) sur la résine adhésive activée. On passe ensuite aux étapes traditionnelles de soudage des fils conducteurs et d'encapsulation pour obtenir le module à semiconducteurs.

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IPC 8 full level

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